



MATERIALS

HOUSING: THERMOPLASTIC BLACK(UL 94V-0).
 TERMINAL: COPPER ALLOY, NICKEL UNDER PLATED OVERALL
 GOLD PLATED OVER ALL
 SHELL:SUS PLATING: NICKEL PLATED OVERALL.
 GOLD PLATED ON SOLDER TAILS

SPECIFICATION

CURRENT RATING: 0.5 AMP AC/DC MAX
 DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE
 CONTACT RESISTANCE: 100m OHMS MAX
 INSULATION RESISTANCE: 1000M OHMS MIN AT DC 250V
 OPERATION TEMPERATURE: -25°C~+85°C

Nano-SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

RoHS Compliant		HSM 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.	
APPD. 核准 HELEN		TOLERANCE LINEAR: X±0.30 .XX±0.20 .XXX±0.10 ANGLES: ±5°	PART NAME 品名 Nano SIM Card Connector 6Pin SMT Type H=1.35mm Gold Flash Plating W/ Locating Peg Black Color Reel Packing ROHS
DWG. 製圖 ABBY	SCALE 比例 參考 UNIT 單位 MM	SIZE. 紙張尺寸 A4	PART NO. 料號 C0657-06DGYBR0R
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